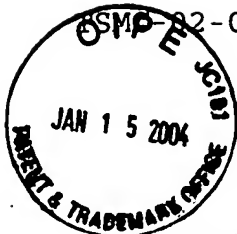


1756



January 5, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/687,178 10/16/03 |  
Jaw-Jung Shin et al.  
A NEW METHOD TO REDUCE CD NON-  
UNIFORMITY IN IC MANUFACTURING  
| \_\_\_\_\_ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on January 13, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date SB 1/13/04

U.S. Patent 5,242,770 to Chen et al., "Mask for Photolithography," reveals a mask for reducing proximity effects using leveling bars.

U.S. Patent 5,821,014 to Chen et al., "Optical Proximity Correction Method for Intermediate-Pitch Features Using Sub-Resolution Scattering Bars on a Mask," discloses an OPC method using scattering bars.

The following three U.S. Patents disclose photo processes using extra shapes to improve image resoltuion:

- 1) U.S. Patent 6,218,089 to Pierrat, "Photolithographic Method."
- 2) U.S. Patent 6,197,452 to Matumoto, "Light Exposure Pattern Mask with Dummy Patterns and Production Method of the Same."
- 3) U.S. Patent 6,109,775 to Tripathi et al., "Method for Adjusting the Density of Lines and Contact Openings Across a Substrate Region for Improving the Chemical-Mechanical Polishing of a Thin-film Later Disposed Thereon."


U.S. Patent 5,946,563 to Uehara et al., "Semiconductor Device and Method of Manufacturing the Same," discloses a semiconductor device and method of manufacturing the same.

TSMC-02-0776

U.S. Patent 6,281,049 to Lee, "Semiconductor Device Mask and Method for Forming the Same," discloses a semiconductor device mask and for a method of creating the mask.

U.S. Patent 6,426,269 to Haffner et al., "Dummy Feature Reduction Using Optical Proximity Effect Correction," discloses a method for the reduction of dummy features by using optical proximity effect correction.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over the printed name.

Stephen B. Ackerman,  
Reg. No. 37761

Form PTO-1449

# INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Document Number (Sequence)

TSMC-02-0776

Application Number

10/687,178

Applicant

Jaw-Jung Shin et al.

Filing Date

10/16/03

Group Art Unit

## U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	PLUNG DATE IF APPROPRIATE
	5242770	9/7/93	Chen et al.	430	5	1/16/92
	5821014	10/13/98	Chen et al.	430	5	2/28/97
	6218089	4/17/01	Pierrat	430	394	5/22/98
	6197452	3/6/01	Matsumoto	430	5	9/16/98
	6109775	8/29/00	Tripathi et al.	364	488	9/8/97
	5946563	8/31/99	Uehara et al.	438	183	6/23/97
	6281049	8/28/01	Lee	438	129	12/23/98
	6426269	7/30/02	Haffner et al.	438	401	10/21/99

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.